

### General Description

The SY20806A is an ultra-low  $R_{DS(ON)}$ , N-channel MOSFET single channel load switch with controlled turn-ON slew rate for minimum power loss. The device has an input voltage range of 1.05 V to 5.5 V and can support a maximum continuous current of 2 A.

The SY20806A small size and ultra-low  $R_{DS(ON)}$  along with very low operating and shutdown currents makes it an ideal choice for space limited, battery powered applications.

In order to prevent the voltage droop during start-up with large capacitive loads, the part features a soft start circuit to reduce the inrush current.

SY20806A integrates a 120  $\Omega$  pull-down resistor for fast output discharge when the switch is open, further reducing the total solution size.

SY20806A uses a small, space saving 0.78mm  $\times$ 0.78mm, 4-pin CSP package with 0.4mm pitch, and 0.5mm height.

The part is designed to operate between of -40  $^{\circ}$ C to +105  $^{\circ}$ C.

### Features

- Input Voltage Range: 1.05V to 5.5V
- 2A Load Current Capability
- Ultra-low  $R_{DS(ON)}$ :
  - 37m $\Omega$ (typ) at  $V_{IN} = 5V$
  - 38m $\Omega$ (typ) at  $V_{IN} = 3.3V$
  - 43m $\Omega$ (typ) at  $V_{IN} = 1.8V$
- Quiescent Current: 9.7 $\mu$ A (typ) at  $V_{IN}=3.3V$
- Shutdown Current: 0.1  $\mu$ A (typ) at  $V_{IN}= 3.3V$
- Controlled Slew Rate:
  - 910 $\mu$ s rise time at  $V_{IN}=3.3V$
- Compact Package: CSP 0.78mm  $\times$ 0.78mm.

### Applications

- Notebook
- Cell Phone
- Digital Cameras
- IoT devices

### Typical Application

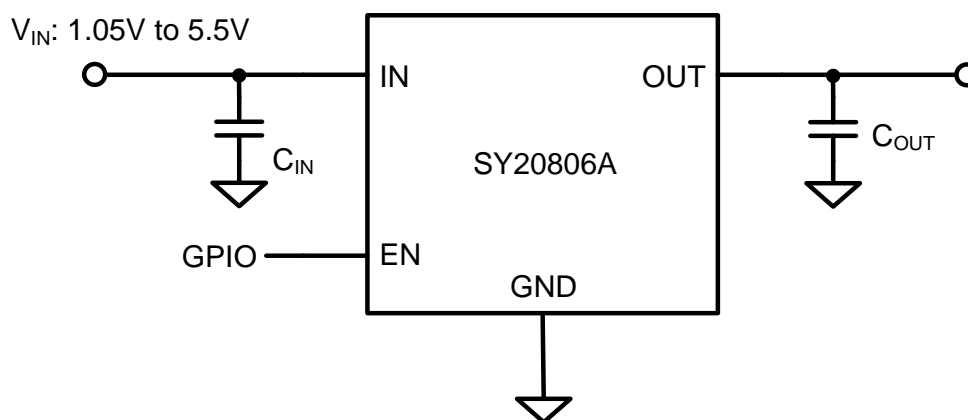


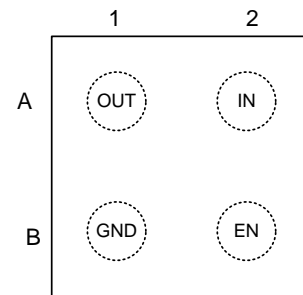
Figure1. Schematic Diagram

## Ordering Information

Ordering Part Number	Package Type	Top Mark
SY20806APAC	CSP0.78×0.78–4 RoHS Compliant and Halogen Free	hGxyz

*x=year code, y=week code, z=lot number code*

## Pinout (top view)



Pin Name	Pin number	Pin Description
IN	A2	Input pin, decoupled with at least a 1 $\mu$ F MLCC capacitor to GND.
GND	B1	Ground pin.
OUT	A1	Output pin, decoupled with a 1 $\mu$ F MLCC capacitor to GND.
EN	B2	ON/OFF control. Do not leave it floating.

## Block Diagram

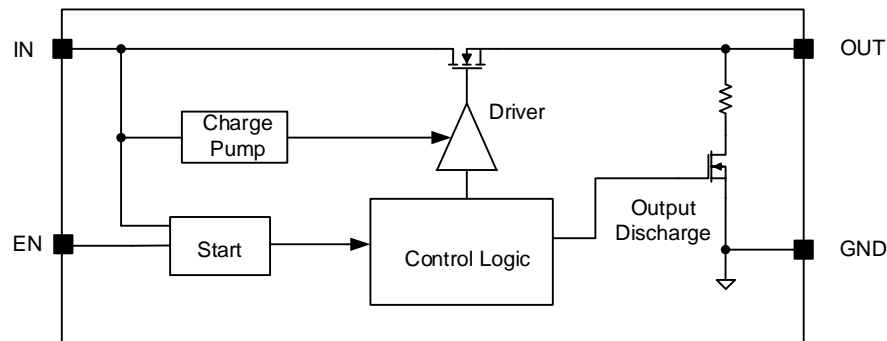


Figure2. Block Diagram

Absolute Maximum Ratings (1)	Min	Max	Unit
IN, OUT, EN to GND	-0.3	6	V
Junction Temperature, Operating	-40	150	°C
Lead Temperature (Soldering, 10sec.)		260	
Storage Temperature	-65	150	

Thermal Information (2)	Typ	Unit
$\theta_{JA}$ Junction-to-ambient Thermal Resistance	193	°C/W
$\theta_{JC}$ Junction-to-case Thermal Resistance	2.3	
$P_D$ Power Dissipation $T_A=25^\circ\text{C}$	0.52	W

ESD Susceptibility	Min	Max	Unit
HBM (Human Body Mode)		2	kV
CDM (Charged Device Mode)		500	V

Recommended Operating Conditions (3)	Min	Max	Unit
IN	1.05	5.5	V
OUT	0	$V_{IN}$	
EN	0	5.5	
Junction Temperature, Operating	-40	125	°C
Ambient Temperature	-40	105	

**Electrical Characteristics** (Unless otherwise noted, the specification in the following table applies over the operating ambient temperature  $-40^\circ\text{C} \leq T_A \leq +105^\circ\text{C}$ . **Typical values are for  $T_A = 25^\circ\text{C}$ .**)

Parameter	Symbol	Test Conditions	$T_A$	Min	Typ	Max	Unit
Quiescent Current	$I_Q$	$V_{IN}=V_{EN}=3.3\text{V}, I_{OUT}=0\text{A}$	$-40^\circ\text{C}$ to $+85^\circ\text{C}$		9.7	12	$\mu\text{A}$
			$-40^\circ\text{C}$ to $+105^\circ\text{C}$			13	$\mu\text{A}$
Shutdown Current	$I_{SHDN}$	$V_{IN}=3.3\text{V}, V_{EN}=0\text{V}, V_{OUT}=0\text{V}$	$-40^\circ\text{C}$ to $+85^\circ\text{C}$		0.1	2	$\mu\text{A}$
			$-40^\circ\text{C}$ to $+105^\circ\text{C}$			3	$\mu\text{A}$
Switch On Resistance	$R_{ON}$	$V_{IN}=5\text{V}, I_{OUT}=200\text{mA}$	$25^\circ\text{C}$		37	41	$\text{m}\Omega$
			$-40^\circ\text{C}$ to $+85^\circ\text{C}$			51	$\text{m}\Omega$
			$-40^\circ\text{C}$ to $+105^\circ\text{C}$			57	$\text{m}\Omega$
		$V_{IN}=3.3\text{V}, I_{OUT}=200\text{mA}$	$25^\circ\text{C}$		38	41	$\text{m}\Omega$
			$-40^\circ\text{C}$ to $+85^\circ\text{C}$			52	$\text{m}\Omega$
			$-40^\circ\text{C}$ to $+105^\circ\text{C}$			58	$\text{m}\Omega$
		$V_{IN}=1.8\text{V}, I_{OUT}=200\text{mA}$	$25^\circ\text{C}$		43	48	$\text{m}\Omega$
			$-40^\circ\text{C}$ to $+85^\circ\text{C}$			59	$\text{m}\Omega$
			$-40^\circ\text{C}$ to $+105^\circ\text{C}$			66	$\text{m}\Omega$
		$V_{IN}=1.2\text{V}, I_{OUT}=200\text{mA}$	$25^\circ\text{C}$		52	59	$\text{m}\Omega$
			$-40^\circ\text{C}$ to $+85^\circ\text{C}$			73	$\text{m}\Omega$
			$-40^\circ\text{C}$ to $+105^\circ\text{C}$			85	$\text{m}\Omega$
$V_{IN}=1.05\text{V}, I_{OUT}=200\text{mA}$	$25^\circ\text{C}$		63	75	$\text{m}\Omega$		
	$-40^\circ\text{C}$ to $+85^\circ\text{C}$			102	$\text{m}\Omega$		
	$-40^\circ\text{C}$ to $+105^\circ\text{C}$			107	$\text{m}\Omega$		
EN Input Logic High	$V_{IH}$	$V_{IN}=1.05\text{V}$ to $5.5\text{V}$	$25^\circ\text{C}$	1			V
EN Input Logic Low	$V_{IL}$	$V_{IN}=1.05\text{V}$ to $5.5\text{V}$	$25^\circ\text{C}$			0.4	V

**Electrical Characteristics** (Unless otherwise noted, the specification in the following table applies over the operating ambient temperature  $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ . **Typical values are for  $T_A = 25^{\circ}\text{C}$ .**)

Parameter	Symbol	Test Conditions	$T_A$	Min	Typ	Max	Unit
EN Hysteresis	$V_{\text{HYS\_EN}}$	$V_{\text{IN}}=5.5\text{V}$	$25^{\circ}\text{C}$		102		mV
		$V_{\text{IN}}=1.05\text{V}$	$25^{\circ}\text{C}$		92		mV
Discharge Resistance	$R_{\text{DSG}}$	$V_{\text{IN}}=V_{\text{OUT}}=3.3\text{V}, V_{\text{EN}}=0\text{V}$	$-40^{\circ}\text{C}$ to $+105^{\circ}\text{C}$		120	180	$\Omega$

## Switching Characteristics

Refer to the timing test circuit in Figure 2 (unless otherwise noted) for references to external components used for the test condition in the switching characteristics table. Switching characteristics shown below are only valid for the power-up sequence where  $V_{\text{IN}}$  is already in steady state condition before the EN pin is asserted high.

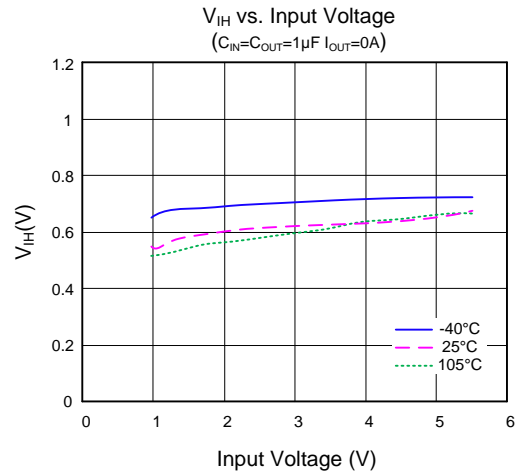
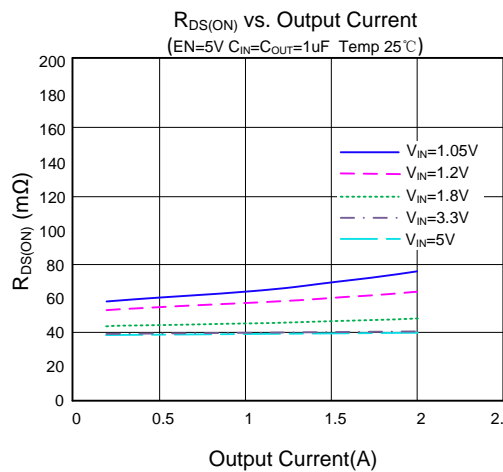
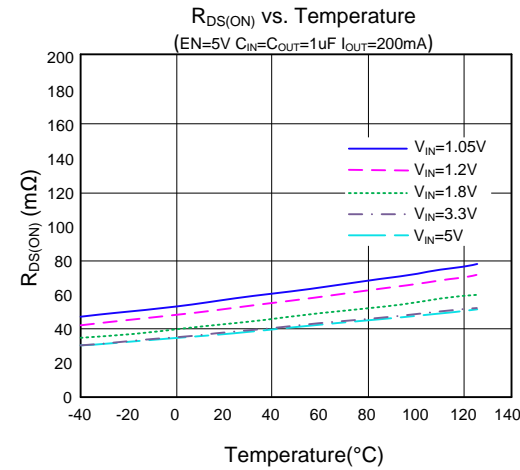
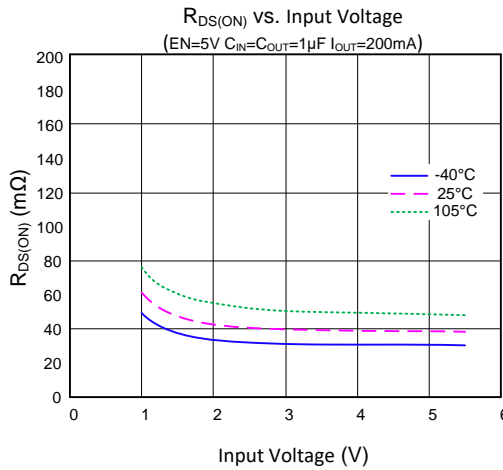
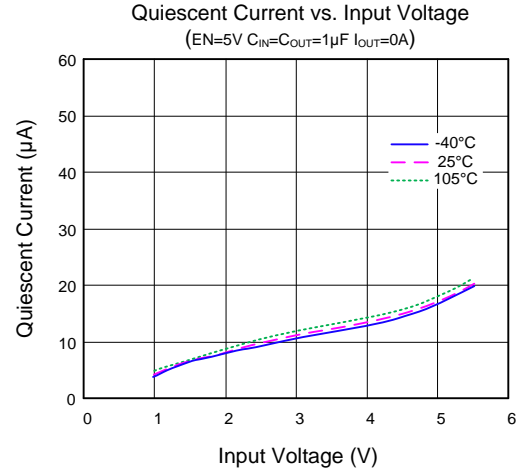
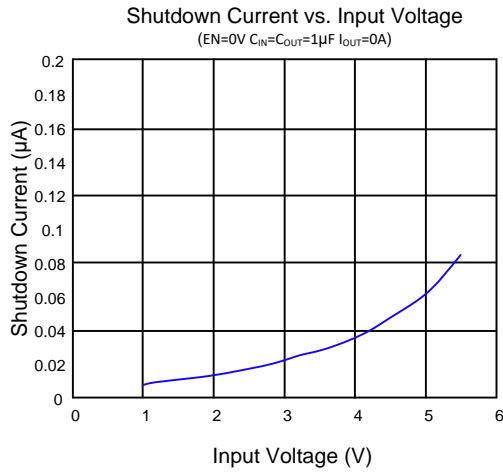
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
$V_{\text{IN}}=5\text{V}, V_{\text{ON}}=5\text{V}, T_A=25^{\circ}\text{C}$ (Unless otherwise noted)						
Turn On Time	$t_{\text{ON}}$	$R_L=10\Omega, C_{\text{IN}}=1\mu\text{F}, C_{\text{OUT}}=0.1\mu\text{F}$		1300		$\mu\text{s}$
Turn Off Time	$t_{\text{OFF}}$	$R_L=10\Omega, C_{\text{IN}}=1\mu\text{F}, C_{\text{OUT}}=0.1\mu\text{F}$		2		$\mu\text{s}$
$V_{\text{OUT}}$ Rise Time	$t_{\text{R}}$	$R_L=10\Omega, C_{\text{IN}}=1\mu\text{F}, C_{\text{OUT}}=0.1\mu\text{F}$		1280		$\mu\text{s}$
$V_{\text{OUT}}$ Fall Time	$t_{\text{F}}$	$R_L=10\Omega, C_{\text{IN}}=1\mu\text{F}, C_{\text{OUT}}=0.1\mu\text{F}$		2		$\mu\text{s}$
Delay Time	$t_{\text{D}}$	$R_L=10\Omega, C_{\text{IN}}=1\mu\text{F}, C_{\text{OUT}}=0.1\mu\text{F}$		660		$\mu\text{s}$
$V_{\text{IN}}=3.3\text{V}, V_{\text{ON}}=5\text{V}, T_A=25^{\circ}\text{C}$ (Unless otherwise noted)						
Turn On Time	$t_{\text{ON}}$	$R_L=10\Omega, C_{\text{IN}}=1\mu\text{F}, C_{\text{OUT}}=0.1\mu\text{F}$		1080		$\mu\text{s}$
Turn Off Time	$t_{\text{OFF}}$	$R_L=10\Omega, C_{\text{IN}}=1\mu\text{F}, C_{\text{OUT}}=0.1\mu\text{F}$		2		$\mu\text{s}$
$V_{\text{OUT}}$ Rise Time	$t_{\text{R}}$	$R_L=10\Omega, C_{\text{IN}}=1\mu\text{F}, C_{\text{OUT}}=0.1\mu\text{F}$		910		$\mu\text{s}$
$V_{\text{OUT}}$ Fall Time	$t_{\text{F}}$	$R_L=10\Omega, C_{\text{IN}}=1\mu\text{F}, C_{\text{OUT}}=0.1\mu\text{F}$		2		$\mu\text{s}$
Delay Time	$t_{\text{D}}$	$R_L=10\Omega, C_{\text{IN}}=1\mu\text{F}, C_{\text{OUT}}=0.1\mu\text{F}$		620		$\mu\text{s}$
$V_{\text{IN}}=1.05\text{V}, V_{\text{ON}}=5\text{V}, T_A=25^{\circ}\text{C}$ (Unless otherwise noted)						
Turn On Time	$t_{\text{ON}}$	$R_L=10\Omega, C_{\text{IN}}=1\mu\text{F}, C_{\text{OUT}}=0.1\mu\text{F}$		750		$\mu\text{s}$
Turn Off Time	$t_{\text{OFF}}$	$R_L=10\Omega, C_{\text{IN}}=1\mu\text{F}, C_{\text{OUT}}=0.1\mu\text{F}$		3		$\mu\text{s}$
$V_{\text{OUT}}$ Rise Time	$t_{\text{R}}$	$R_L=10\Omega, C_{\text{IN}}=1\mu\text{F}, C_{\text{OUT}}=0.1\mu\text{F}$		410		$\mu\text{s}$
$V_{\text{OUT}}$ Fall Time	$t_{\text{F}}$	$R_L=10\Omega, C_{\text{IN}}=1\mu\text{F}, C_{\text{OUT}}=0.1\mu\text{F}$		2		$\mu\text{s}$
Delay Time	$t_{\text{D}}$	$R_L=10\Omega, C_{\text{IN}}=1\mu\text{F}, C_{\text{OUT}}=0.1\mu\text{F}$		550		$\mu\text{s}$

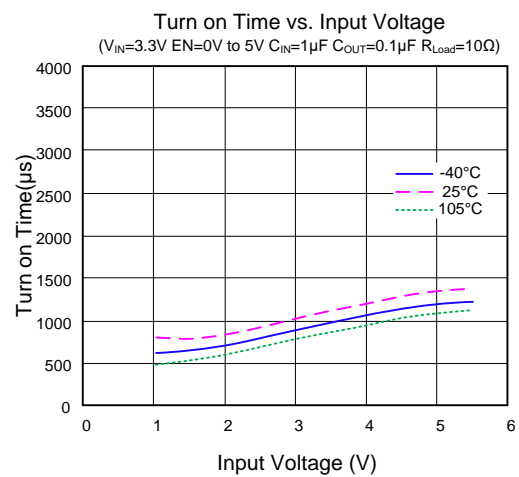
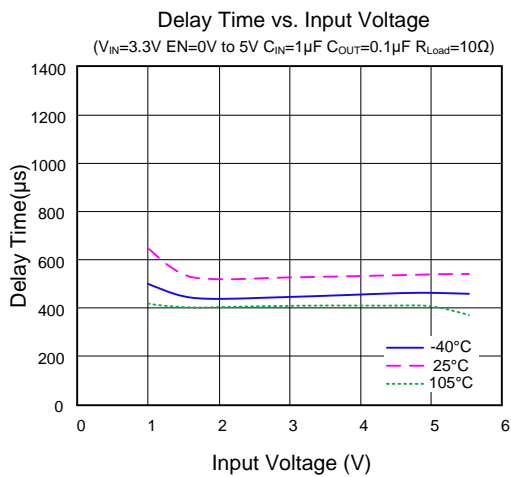
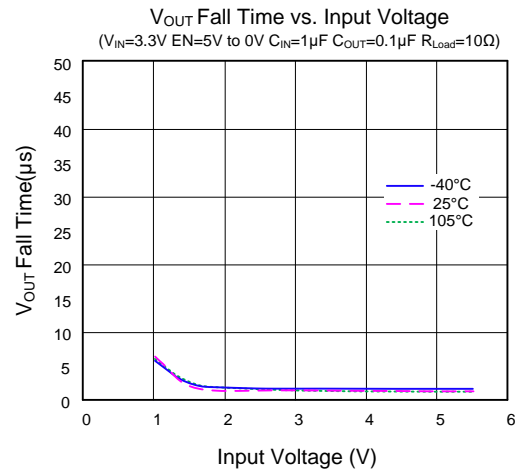
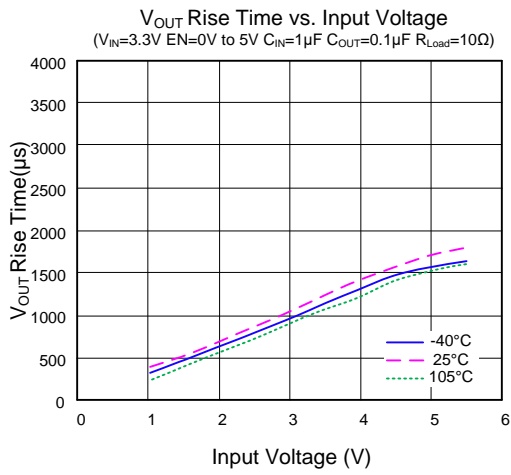
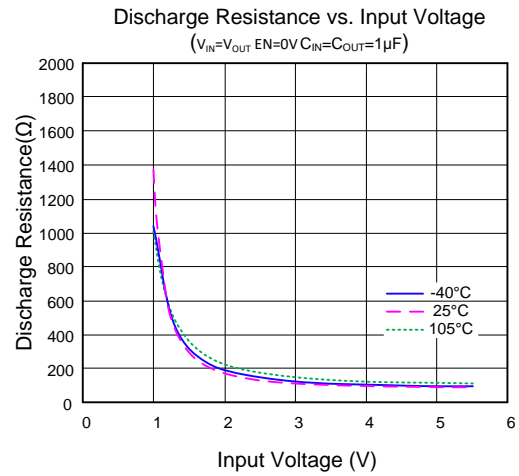
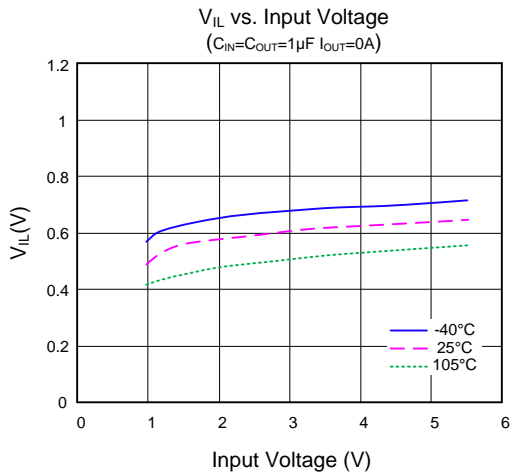
**Note 1:** Stresses beyond the “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

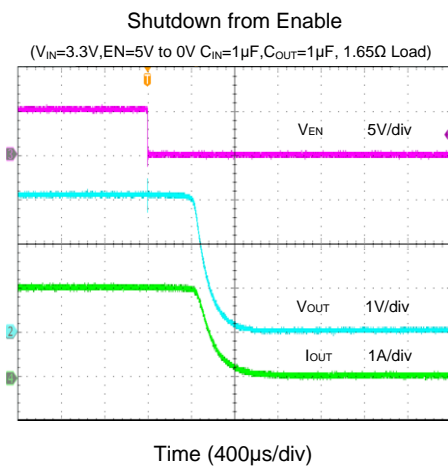
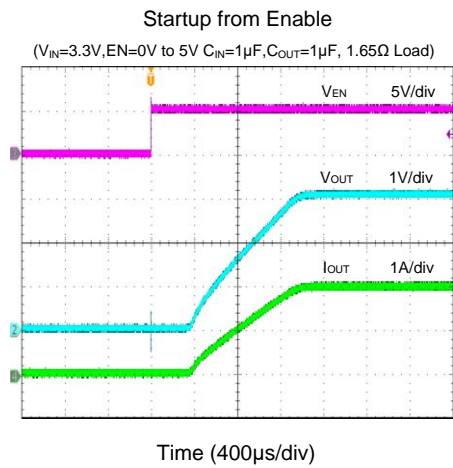
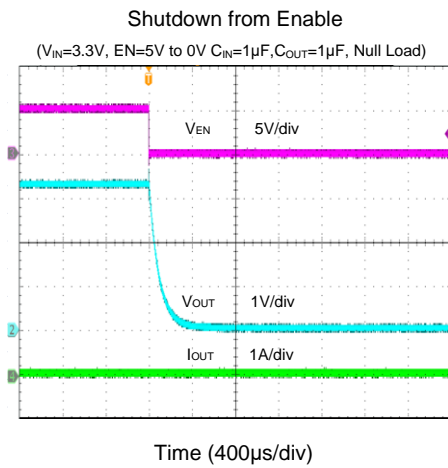
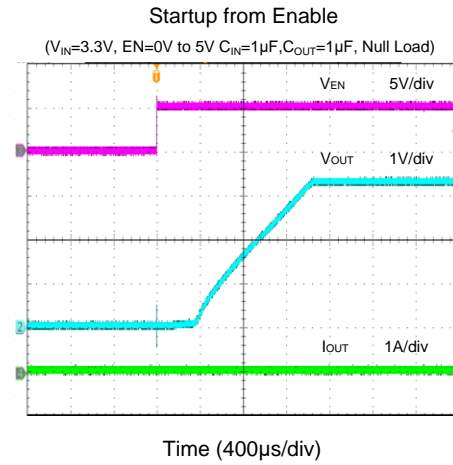
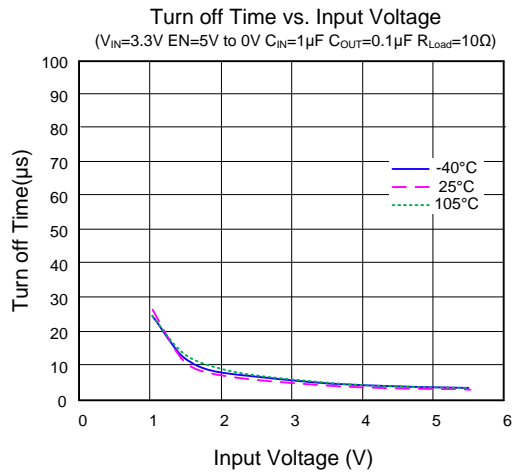
**Note 2:**  $\theta_{\text{JA}}$  is measured in the natural convection at  $T_A = 25^{\circ}\text{C}$  on a low effective single layer thermal conductivity test board of JEDEC 51-3 thermal measurement standard.

**Note 3:** The device is not guaranteed to function outside its operating conditions.

## Typical Operating Characteristics







## Operation

The SY20806A is an ultra-low  $R_{DS(ON)}$ , N-channel MOSFET single channel load switch with controlled slew rate for minimum power loss. The device has an input voltage range of 1.05 V to 5.5 V and can support a maximum continuous current of 2 A. The device is controlled by the EN input, which can directly interface with low-voltage control signals.

## Application Information

### Input Capacitor

To reduce device inrush current, a  $1\mu\text{F}$  ceramic capacitor,  $C_{IN}$ , is recommended. A higher value of  $C_{IN}$  can be used to reduce the voltage drop experienced as the switch is turned ON into a large capacitive load. To optimize operation,  $C_{IN}$  should be placed as close as possible to the IN and GND pins.

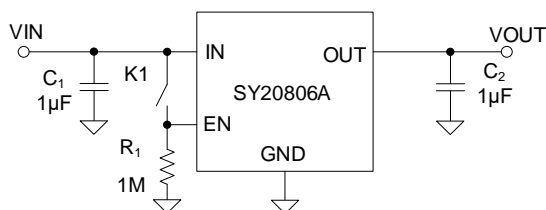
### Output Capacitor

A  $1\mu\text{F}$  ceramic output cap is recommended to prevent parasitic board inductance from forcing OUT below GND when turning off.

### Output Discharge

SY20806A integrates a  $120\ \Omega$  (typ) pull-down resistor for fast output discharge when the switch is turned OFF, further reducing the size of the overall solution.

### Application Schematic



### BOM List

Designator	Description	Part Number	Manufacturer
$C_1, C_2$	$1\mu\text{F}/50\text{V}$ , 0603, X5R	GRM188R61H105K	Murata
$R_1$	$1\text{M}\Omega$ , 0603	RC0603FR-071ML	YAGEO

## PCB Layout Guide

For best performance of the SY20806APAC, the following guidelines must be followed:

- ✧ Keep all power traces as short and wide as possible and use at least 1-ounce copper for all power traces.
- ✧ Place a ground plane under all circuitry to lower both resistance and inductance, and improve DC and transient performance.
- ✧ Place the output capacitors as close to the connectors as possible, to lower the impedance (mainly inductance) between the part and the capacitor and improve transient performance.
- ✧ Input and output capacitors should be placed close to the IC and connected to ground plane to reduce noise coupling.

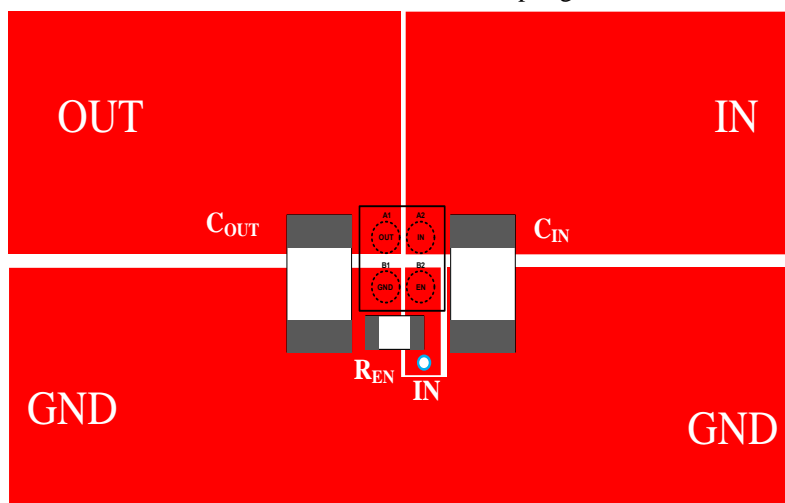
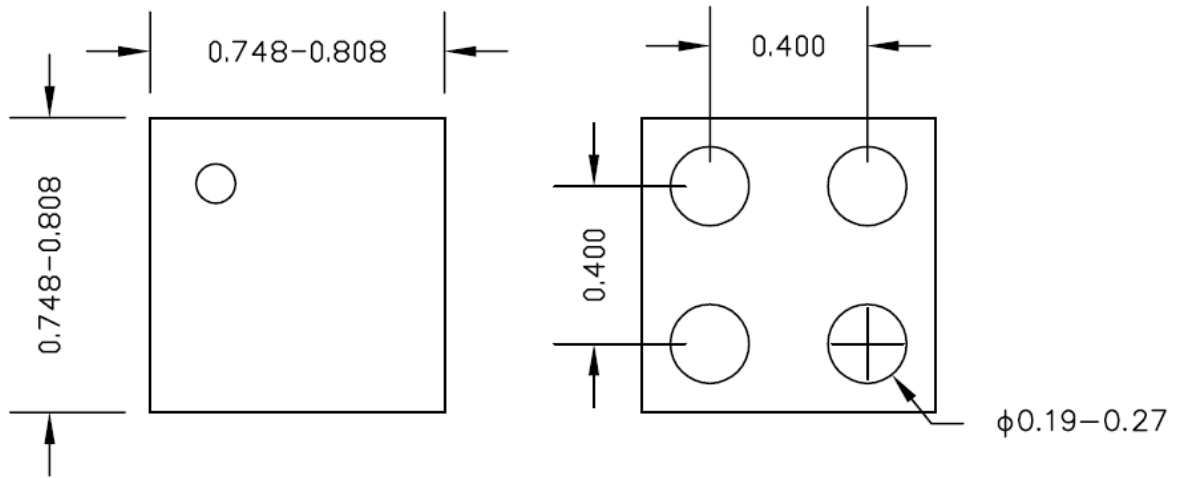


Figure3. PCB Layout Suggestion

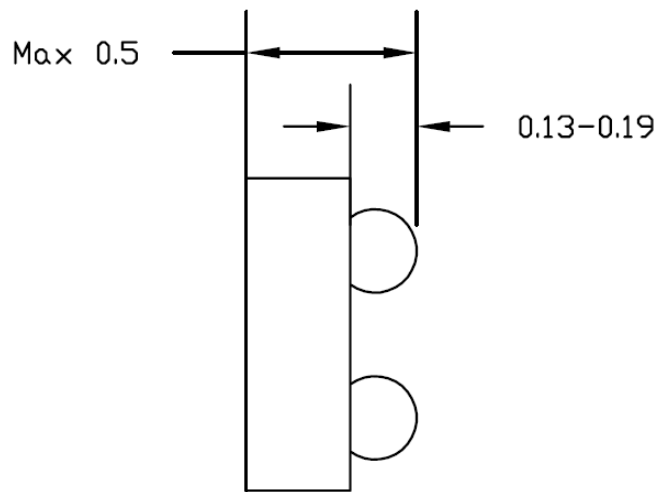


**CSP0.78×0.78-4 Package Outline**



**Top View**

**Bottom View**



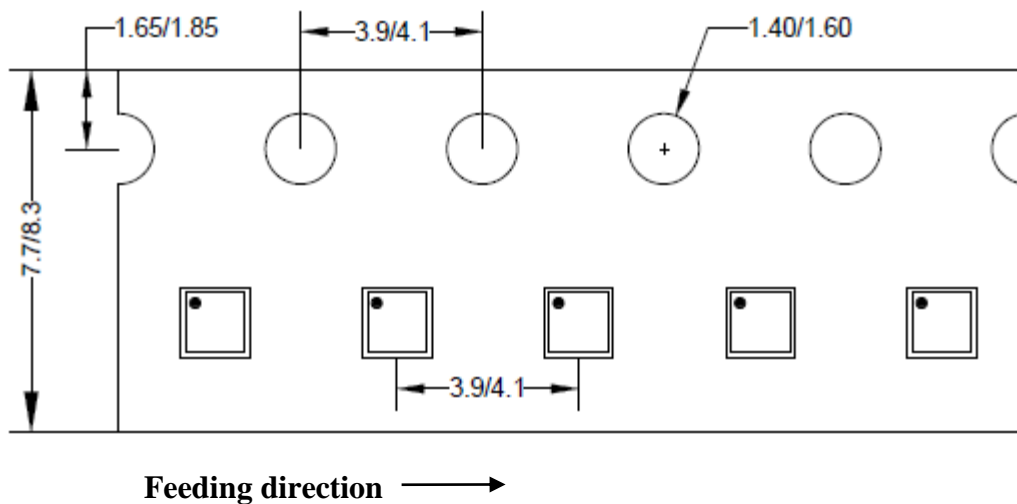
**Side View**

**Notes: All dimension in millimeter and exclude mold flash & metal burr.**

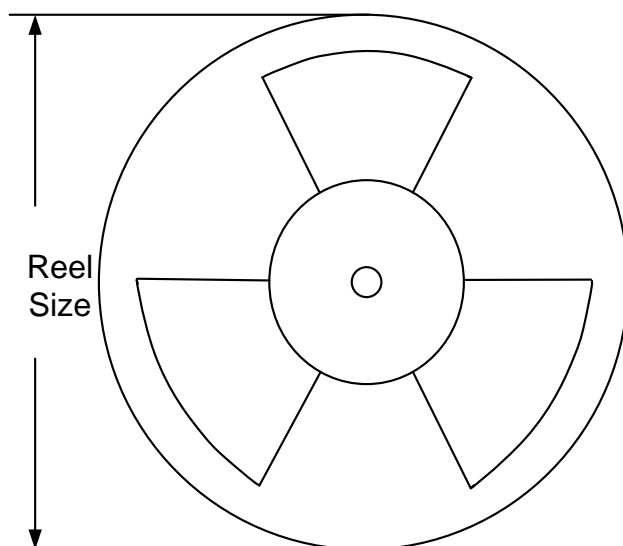
**Taping & Reel Specification**

**1. Taping orientation**

**CSP0.78×0.78**



**2. Carrier Tape & Reel specification for packages**



Package type	Tape width (mm)	Pocket pitch(mm)	Reel size (Inch)	Trailer length(mm)	Leader length (mm)	Qty per reel
CSP0.78×0.78	8	4	7"	400	160	5000

**3. Others: NA**

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## Revision History

The revision history provided is for informational purpose only and is believed to be accurate, however, not warranted. Please make sure that you have the latest revision.

<b>Date</b>	<b>Revision</b>	<b>Change</b>
Aug.20, 2021	Revision 1.0	Production Release.
Aug.14, 2020	Revision 0.9	Initial Release.

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